

מענקי מחקר ופיתוח לשנת 2017

בנושאי רכיבים ומערכות

Focus:

- Integration and mastering of complexity of electronics and materials into miniaturised systems for a broad spectrum of use
- Integration of digital technology in the next wave of products

Funding Tools for Israeli Partners: Horizon 2020

- Consortium - At least 3 partners from 3 different European Member States (including Israel)
- Funding tools:
 - Research & Innovation Action (RIA) - Development of new technology, product, service or solution – 100%
 - Innovation Action (IA) - Implementation of R&D results – 70%
 - SME Instrument - Phase 1 - feasibility study (50 K€ per project), Phase 2 - innovation projects (70% funding), Phase 3 - indirect support measures and services (no funding)
- Indirect costs - 25%
- No Royalties payment
- IPR - no EU share of the developed IP

Relevant Agendas and Platforms:

- **EPoSS** - European Technology Platform on Smart Systems Integration: <http://www.smart-systems-integration.org/public>
- **ARTEMIS** - Embedded Computing Systems Initiative: <http://www.artemis-ju.eu/>



Objective	Funding Tools	Budget	Deadline
ICT-04-2017: Smart Anything Everywhere Initiative			
a. Collaborate on building the European "Smart Anything Everywhere" ecosystem: Cyber-physical and embedded systems, customised low energy computing powering CPS and the IoT, advanced micro-electronics components and Smart System Integration (up to 7 M€ per project), and organic and large area electronics (up to 4.5 M€ per project)	Innovation (70%)	25.5 M€	8 November 2016
b. Increase the outreach of the actions and their impact, to achieve a wider coverage of stakeholders in technological, application, innovation, and geographic terms (1 M€ per project)	Coordination & Support (100%)	1 M€	
NMBP-13-2017: Cross-cutting KETs for diagnostics at the point-of-care			
Novel technological Micro-Nano–Bio integrated Systems (MNBS) platforms to enhance the ability to sense, detect, analyse, monitor and act on phenomena from macro to nano scale (3-5 M€ for a project)	Research & Innovation (100%)	15 M€	19 January 2017
ECSEL: the Electronic Components and Systems Joint Undertaking			
Electronic Components and Systems – Smart mobility, society, energy, health, production. Semiconductor process equipment materials, design technologies, cyber-physical systems	Research & Innovation Action & Innovation Action	~400 M€	24 May 2016, 20 September 2016

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